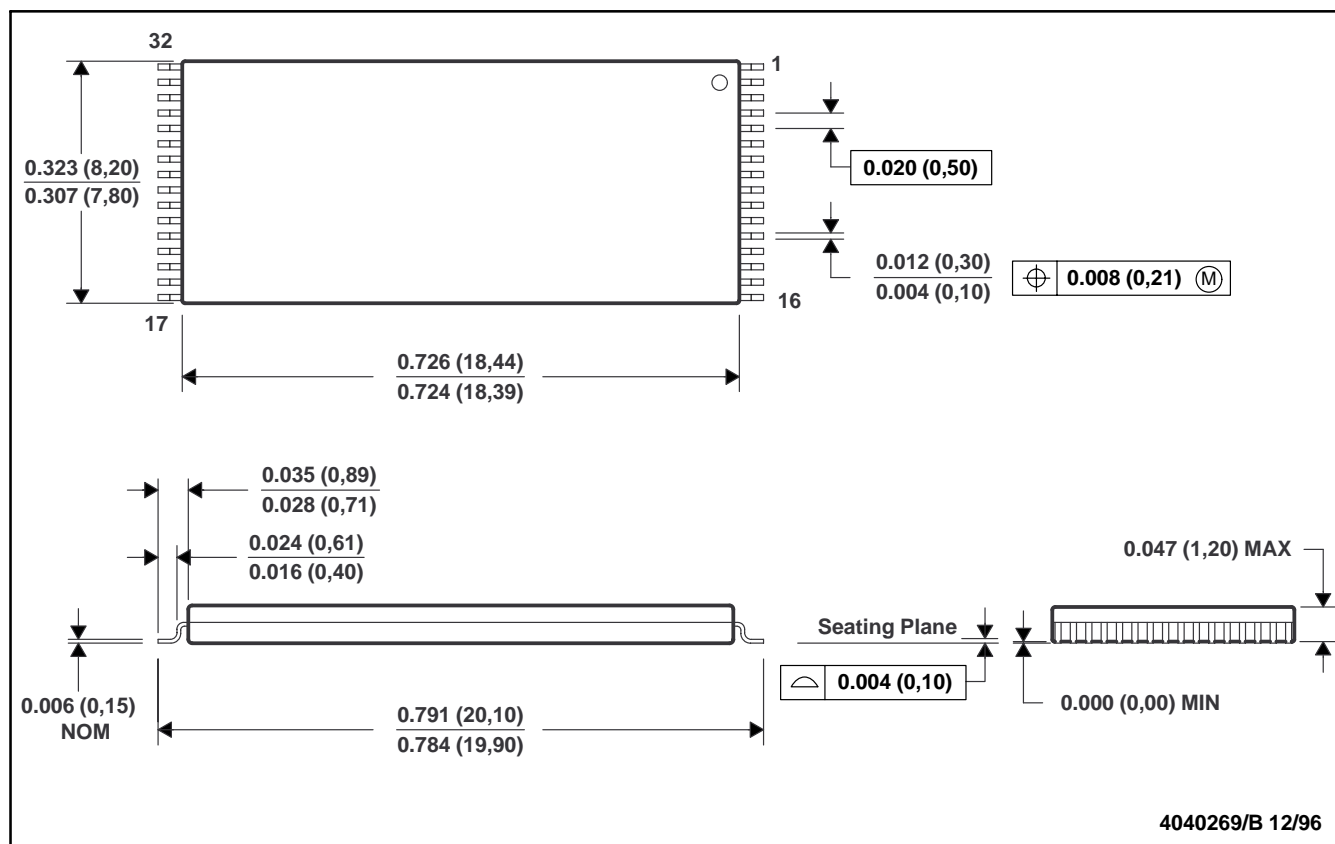


DU (R-PDSO-G32)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package is a reverse pin configuration to the DD package.

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